



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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# MA2S1110G

## Silicon epitaxial planar type

For switching circuits

### ■ Features

- Allowing high-density mounting
- Short reverse recovery time  $t_{rr}$
- Small terminal capacitance  $C_t$

### ■ Package

- Code  
SSMini2-F4
- Pin Name  
1: Anode  
2: Cathode

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

| Parameter                                   | Symbol    | Rating      | Unit             |
|---|-----------|-------------|------------------|
| Reverse voltage                             | $V_R$     | 80          | V                |
| Maximum peak reverse voltage                | $V_{RM}$  | 80          | V                |
| Forward current                             | $I_F$     | 100         | mA               |
| Peak forward current                        | $I_{FM}$  | 225         | mA               |
| Non-repetitive peak forward surge current * | $I_{FSM}$ | 500         | mA               |
| Junction temperature                        | $T_j$     | 150         | $^\circ\text{C}$ |
| Storage temperature                         | $T_{stg}$ | -55 to +150 | $^\circ\text{C}$ |

### ■ Marking Symbol: A

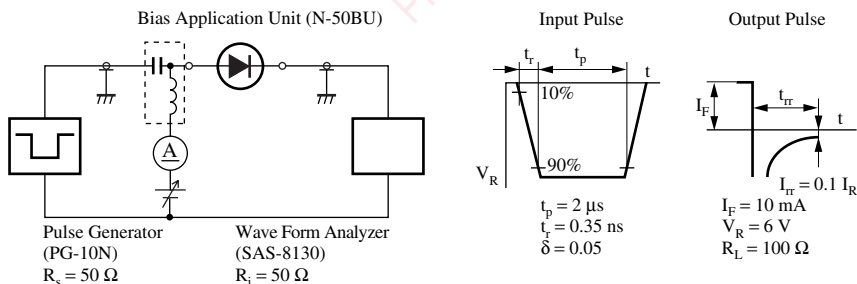
Note) \*:  $t = 1\text{ s}$

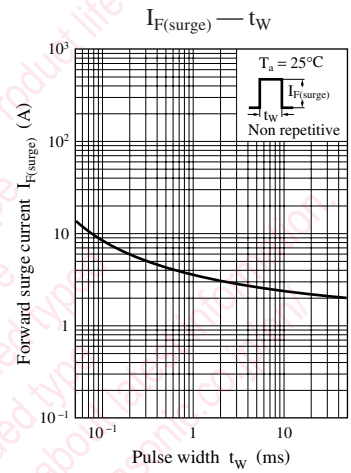
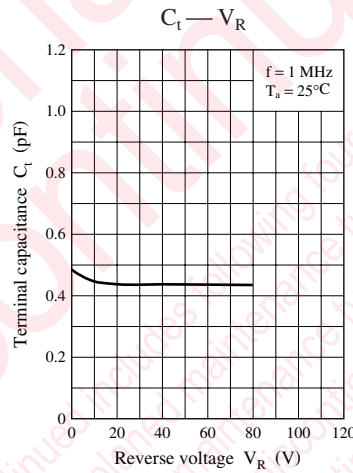
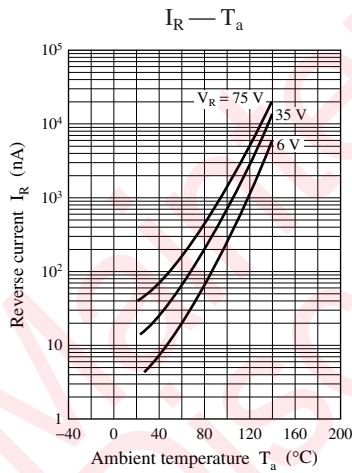
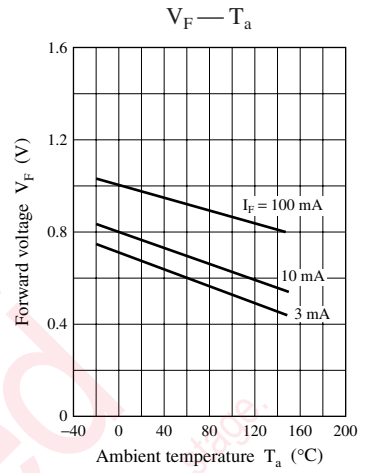
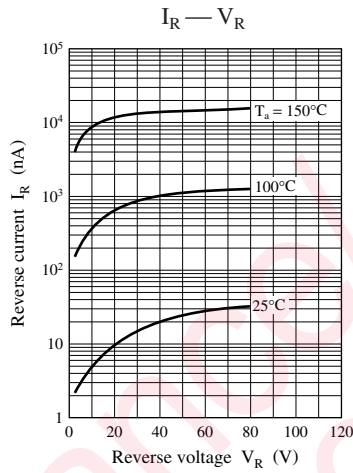
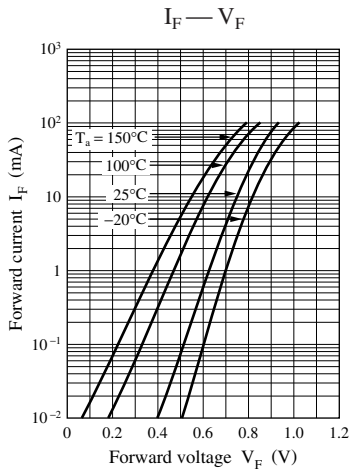
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

| Parameter               | Symbol   | Conditions  | Min | Typ  | Max  | Unit |
|-------------------------|----------|---|-----|------|------|------|
| Forward voltage         | $V_F$    | $I_F = 100\text{ mA}$   |     | 0.95 | 1.20 | V    |
| Reverse voltage         | $V_R$    | $I_R = 100\ \mu\text{A}$  | 80  |      |      | V    |
| Reverse current         | $I_R$    | $V_R = 75\text{ V}$   |     |      | 100  | nA   |
| Terminal capacitance    | $C_t$    | $V_R = 0\text{ V}, f = 1\text{ MHz}$  |     | 0.6  | 2.0  | pF   |
| Reverse recovery time * | $t_{rr}$ | $I_F = 10\text{ mA}, V_R = 6\text{ V}$<br>$I_{tr} = 0.1 I_R, R_L = 100\ \Omega$ |     |      | 3    | ns   |

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

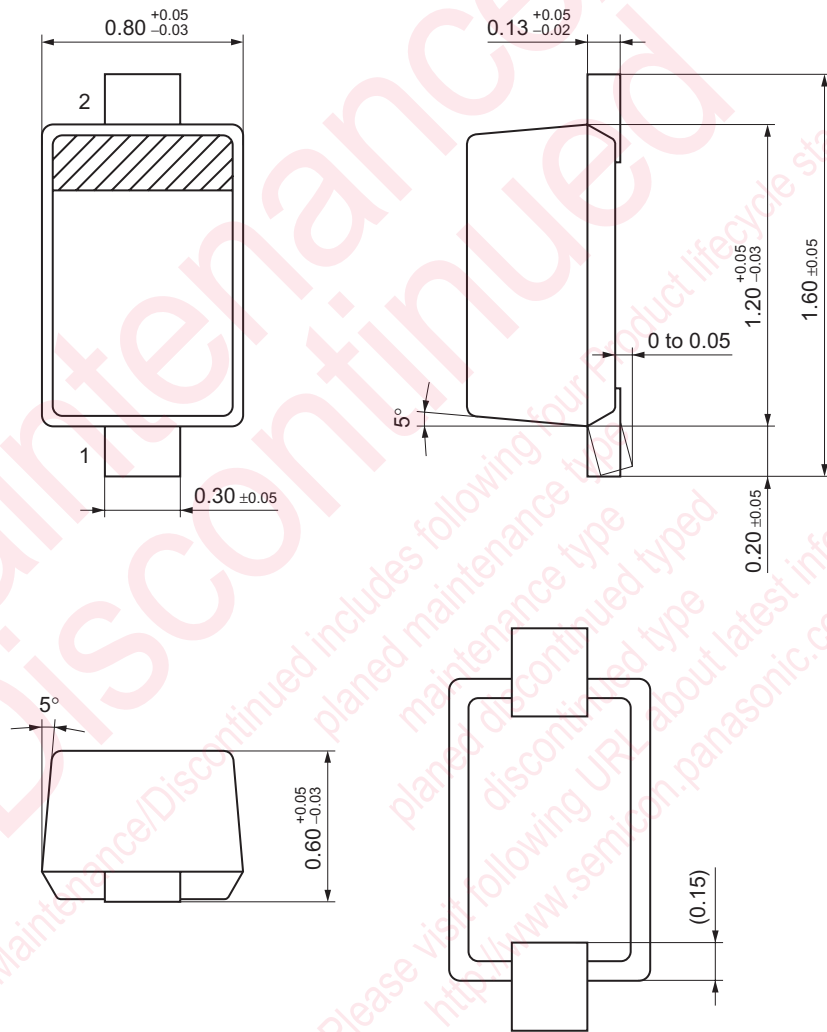
2. Absolute frequency of input and output is 100 MHz.
3. \*:  $t_{rr}$  measurement circuit





SSMini2-F4

Unit: mm



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